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APPLICATION NO.	FI	LING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/822,712	22,712 04/13/2004		Jin-Chyung Biar	BIAR3001/EM	3031	
23364	7590	03/23/2005		EXAMI	EXAMINER	
BACON &	& THOMA	S, PLLC	CLARK, SHEILA V			
625 SLATE	ERS LANE					
FOURTH F	FLOOR		ART UNIT	PAPER NUMBER		
ALEXANDRIA, VA 22314				2815		

DATE MAILED: 03/23/2005

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Applicant(s)	
	10/822,712	BIAR ET AL	(m)
Office Action Summary	Examiner	Art Unit	
	S. V. Clark	2815	
The MAILING DATE of this communication a Period for Reply	ppears on the cover sheet	with the correspondence addre	:ss
A SHORTENED STATUTORY PERIOD FOR REF THE MAILING DATE OF THIS COMMUNICATION - Extensions of time may be available under the provisions of 37 CFR after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a rr - If NO period for reply is specified above, the maximum statutory perions - Failure to reply within the set or extended period for reply will, by state Any reply received by the Office later than three months after the main earned patent term adjustment. See 37 CFR 1.704(b).	N. 1.136(a). In no event, however, may eply within the statutory minimum of to d will apply and will expire SIX (6) M ute, cause the application to become	a reply be timely filed hirty (30) days will be considered timely. ONTHS from the mailing date of this comm ABANDONED (35 U.S.C. § 133).	unication.
Status			
Responsive to communication(s) filed on 2a) ☐ This action is FINAL. 2b) ☒ The street of the second tree of the seco	nis action is non-final. vance except for formal m	•	erits is
Disposition of Claims			
4) ☐ Claim(s) 1-11 is/are pending in the application 4a) Of the above claim(s) is/are withdress 5) ☐ Claim(s) is/are allowed. 6) ☐ Claim(s) 1-11 is/are rejected. 7) ☐ Claim(s) is/are objected to. 8) ☐ Claim(s) are subject to restriction and	rawn from consideration.		
Application Papers			
9) The specification is objected to by the Exami 10) The drawing(s) filed on is/are: a) and an applicant may not request that any objection to the Replacement drawing sheet(s) including the correction. 11) The oath or declaration is objected to by the	ccepted or b) objected on objected on objected one drawing(s) be held in abey ection is required if the drawi	vance. See 37 CFR 1.85(a). ng(s) is objected to. See 37 CFR	` '
Priority under 35 U.S.C. § 119			
12) Acknowledgment is made of a claim for foreign a) All b) Some * c) None of: 1. Certified copies of the priority docume 2. Certified copies of the priority docume 3. Copies of the certified copies of the priority docume application from the International Bure * See the attached detailed Office action for a limit	ents have been received. ents have been received in riority documents have be eau (PCT Rule 17.2(a)).	a Application No en received in this National Sta	age
Attachment(s)	·		
Notice of References Cited (PTO-892) Notice of Draftsperson's Patent Drawing Review (PTO-948) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/0 Paper No(s)/Mail Date	Paper N	w Summary (PTO-413) lo(s)/Mail Date of Informal Patent Application (PTO-15	52)

Application/Control Number: 10/822,712

Art Unit: 2815

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that

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form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United

States.

Claims 1-11 are rejected under 35 U.S.C. 102(b) as being anticipated by

Nakamura.

Nakamura et al shows a stacked semiconductor device comprising a substrate 2

having a conductor pattern (see col.2, lines 36-37, 39-40) and a cavity having a first top

die 1 therein and electrically connected to the conductor patter via wires 3. A second

bottom die 1 is shown stacked on the first die and electrically connected to the

conductor pattern via wires 3 and a insulating layer sealing resin 4 is provided on the

substrate and cover the first die and second die (see col. 5, 58-64). An adhesive resin

layer 4 can also be formed between the first and second die (see col.2, lines 56-57).

First and second dies are shown one on top of the other and they therefore cross each

other.

Claims 1-11 are rejected.

Fogal et al, Morinaga et al, Suh et al are cited to show stacked chips formed in substrate cavities.

Any inquiry concerning this communication should be directed to S. V. Clark at telephone number

(571) 272-1725.

S. V. Clark

Primary Examiner

Art Unit 2815

March 19, 2005